



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cohen, et al.

Serial No.: 09/388,989

Confirmation No.: Unknown

Filed: September 2, 1999

For: Sequential Sputter And  
Reactive Precleans Of  
Vias And Contacts

Group Art Unit: 1762

Examiner: M. Padgett

RECEIVED

AUG 28 2001

OFFICE OF PETITIONS

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

**CERTIFICATE OF MAILING**  
**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on 8-24-01 with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

8-24-01  
Date

Reza Mullah  
Signature

**RESPONSE TO OFFICE ACTION DATED OCTOBER 27, 2000**

In response to the Office Action dated October 27, 2000, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. The Commissioner is authorized to charge \$304.00 for two additional independent claims and eight additional total claims to Deposit Account No. 50-1074/3191.03/BTP, along with any other fees to make this response timely.

**IN THE CLAIMS:**

Please cancel claims ~~2, 5, 7, 15, and 16~~ without prejudice, and replace the claims as follows:

1. (Amended) A method for improving metal deposition on a patterned dielectric layer, comprising:
- a) cleaning the patterned dielectric layer in a processing chamber with a first plasma comprising predominantly argon;